

Title (en)

ASSEMBLY USED FOR COOLING A CIRCUIT BOARD OR SIMILAR

Title (de)

ANORDNUNG FÜR DIE KÜHLUNG EINER LEITERPLATTE ODER DERGLEICHEN

Title (fr)

DISPOSITIF POUR REFROIDIR UNE CARTE DE CIRCUITS OU SIMILAIRE

Publication

EP 1702165 B1 20151230 (DE)

Application

EP 05791377 A 20051004

Priority

- EP 2005010652 W 20051004
- DE 202004019747 U 20041019
- DE 202005015079 U 20050919

Abstract (en)

[origin: WO2006042635A1] Disclosed is a supporting frame (104) that is to be mounted on a printed circuit board (2), is embodied like a drilling rig, and comprises a platform (117) which is provided with supporting legs (105, 106, 107, 108) for fixing the same to the circuit board (2). The center of the platform (42) of the supporting frame (104) encompasses a depression (121, 123) which is configured for assembling a fan (3) at a distance from the circuit board (2). The outer wall (123) of the depression (121, 123) forms part of the fan.

IPC 8 full level

F04D 29/54 (2006.01)

CPC (source: EP US)

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Citation (examination)

- WO 9907196 A2 19990211 - CHECCHETTI MAURIZIO [IT]
- US 5975194 A 19991102 - WAGNER GUY R [US], et al
- US 6130820 A 20001010 - KONSTAD ROLF A [US], et al

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